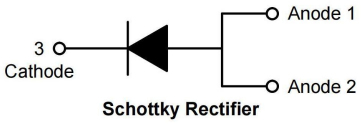
OM SENI

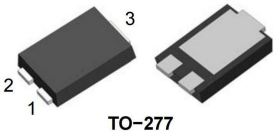
Ultra-Low VF Schottky Rectifier, 8 A, 100 V FSV8100V

Features

- Ultra−Low Forward Voltage Drop
- Low Thermal Resistance
- Very Low Profile: Typical Height of 1.1 mm
- Trench Schottky Technology
- Non−DAP Option Only
- These Devices are Pb−Free, Halogen Free Free and are RoHS Compliant



Schottky Rectifier

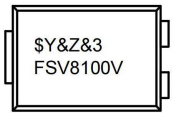


TO−277
CASE 340BQ

Applications

- AC−DC and DC−DC Converter
- Mobile Charger
- LED Lighting
- Solar Panel
- Reverse Polarity Protection

MARKING DIAGRAM



$Y	= OM SENI
&Z	= Assembly Plant Code
&3	= Date Code (Year & Week)
FSV8100V	= Specific Device Code

Specifications

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

Symbol	Rating	Value	Unit
V_{RRM}	Peak Repetitive Reverse Voltage	100	V
V_{RWM}	Working Peak Reverse Voltage	100	V
V_{RMS}	RMS Reverse Voltage	70	V
V_R	DC Blocking Voltage	100	V
$I_{F(AV)}$	Average Rectified Peak Forward Surge Current	8	A
I_{FSM}	Non−Repetitive Peak Forward Surge Current	150	A
T_J	Operating Junction Temperature Range	−55 to +150	°C
T_{STG}	Storage Temperature Range	−55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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THERMAL CHARACTERISTICS (T_A = 25°C unless otherwise noted) (Note 1)

Symbol	Characteristic	Minimum Land Pattern	Maximum Land Pattern	Unit
$R_{\theta JA}$	Junction−to−Ambient Thermal Resistance	100	40	°C/W
Ψ_{JL}	Junction−to−Lead Thermal Characteristics, Thermocouple Soldered to Anode	15	12	°C/W
	Junction−to−Lead Thermal Characteristics, Thermocouple Soldered to Cathode	6	5	

1. The thermal resistances ($R_{\theta JA}$ & Ψ_{JL}) are characterized with device mounted on the following FR4 printed circuit boards, as shown in Figure 1 and Figure 2. PCB size: 76.2 x 114.3 mm. Minimum land pattern size: 4.9 x 4.8 mm (big pattern, x1), 1.4 x 1.52 mm (small pattern, x2). Maximum land pattern size: 30 x 30 mm (pattern, x2). Force line trace size = 55 mils, sense line trace size = 4 mils.



Figure 1. Minimum Land Pattern of 2 oz Copper

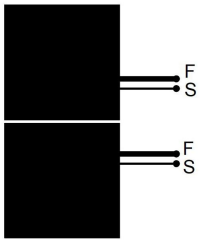

Figure 2. Maximum Land Pattern of 2 oz Copper

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
BV_R	Breakdown Voltage	I_R = 0.5 mA	100	−	−	V
V_F	Forward Voltage Drop	I_F = 5 A	−	0.542	−	V
		I_F = 5 A, T_A = 125°C	−	0.496	−	
		I_F = 8 A	−	0.620	0.670	
		I_F = 8 A, T_A = 125°C	−	0.574	0.600	
		I_F = 10 A	−	0.674	−	
		I_F = 10 A, T_A = 125°C	−	0.611	−	
I_R	Reverse Current	V_R = 70 V	−	0.006	−	mA
		V_R = 70 V, T_A = 125°C	−	5.57	−	
		V_R = 100 V	−	0.008	0.05	
		V_R = 100 V, T_A = 125°C	−	15.65	20	
C_J	Junction Capacitance	V_R = 4 V, f = 1 MHz	−	672	−	pF
T_{rr}	Reverse Recovery Time	I_F = 0.5 A, I_R = 1 A, I_{rr} = 0.25 A	−	19.64	−	ns

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TYPICAL PERFORMANCE CHARACTERISTICS

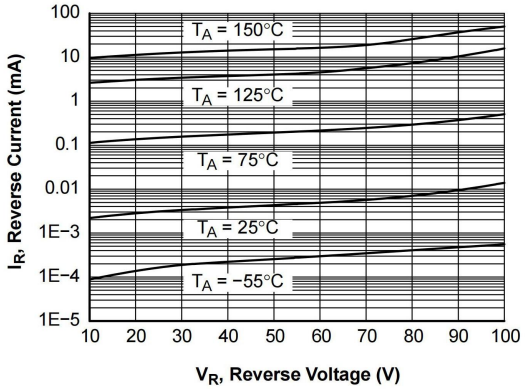

Figure 3. Typical Reverse Characteristics

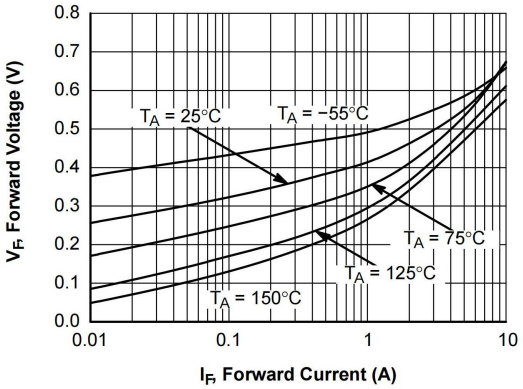

Figure 4. Typical Forward Characteristics

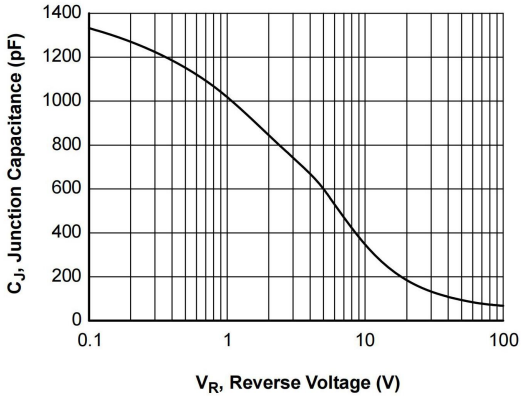

Figure 5. Typical Junction Capacitance

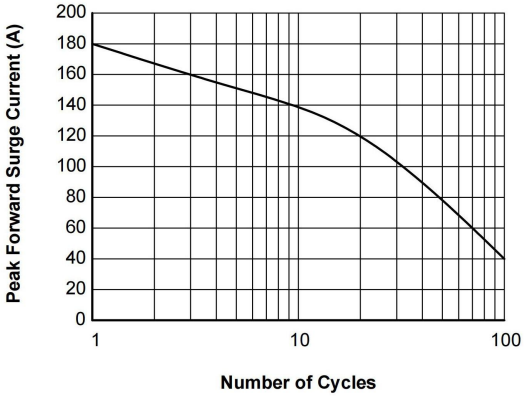

Figure 6. Maximum Non−Repetitive Peak Forward Surge Current

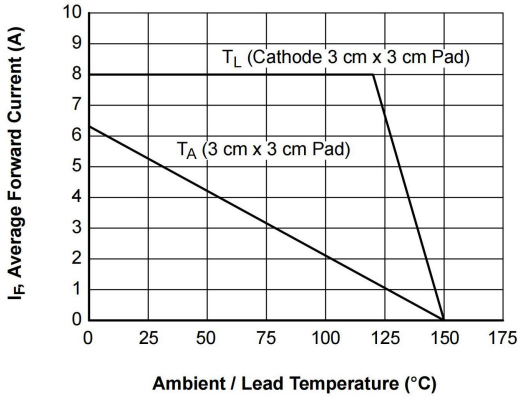

Figure 7. Forward Current Derating Curve

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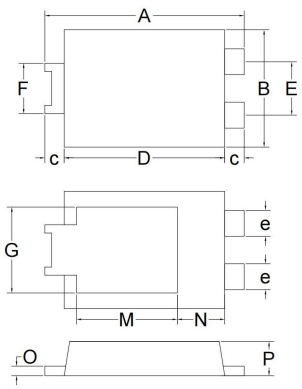
Ordering Information

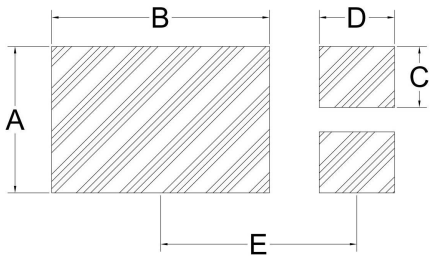
PACKAGE	PACKAGE CODE	UNIT WEIGHT(g)	REEL(pcs)	BOX(pcs)	CARTON(pcs)	DELIVERY MODE
TO-277	R3	0.090	5000	10000	100000	13''

Package Outline Dimensions (TO-277)



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	6.300	6.700	0.248	0.264
B	3.950	4.300	0.156	0.169
c	0.410	0.710	0.016	0.028
D	5.280	5.880	0.208	0.231
E	1.760	1.960	0.069	0.077
e	0.850	0.960	0.033	0.038
F	1.750	1.850	0.069	0.073
G	2.850	3.150	0.112	0.124
M	3.390	3.690	0.133	0.145
N	1.440	1.740	0.057	0.069
O	0.250	0.350	0.010	0.014
P	0.950	1.250	0.037	0.049

Suggested Pad Layout



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	3.400	3.800	0.134	0.150
B	4.500	4.900	0.177	0.193
C	1.200	1.600	0.047	0.063
D	0.600	1.00	0.024	0.039
E	3.670	4.070	0.144	0.160